

PMP10507 BOM

Comment	Description	Designator	Footprint	LibRef	Quantity
GRM1885C1H101JA01D	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	C1	0603L	GRM1885C1H101JA01D	1
GRM21BR71H105KA12L	CAP, CERM, 1uF, 50V, +/-10%, X7R, 0805	C2	0805L	GRM21BR71H105KA12L	1
GRM188R71C105KA12D	CAP, CERM, 1uF, 16V, +/-10%, X7R, 0603	C3, C12, C13, C15, C16, C18	0603L	GRM188R71C105KA12D	6
GRM1885C1H561JA01D	CAP, CERM, 560 pF, 50 V, +/- 5%, C0G/NP0, 0603	C4	0603	GRM1885C1H561JA01D	1
06035C104KAT2A	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0603	C5	0603	06035C104KAT2A	1
GRM188R71H102KA01D	CAP, CERM, 1000 pF, 50 V, +/- 10%, X7R, 0603	C6	0603	GRM188R71H102KA01D	1
C0603C223K3RACTU	CAP, CERM, 0.022uF, 25V, +/-10%, X7R, 0603	C7	0603	C0603C223K3RACTU	1
GRM188R71H102KA01D	CAP, CERM, 1000pF, 50V, +/-10%, X7R, 0603	C8	0603L	GRM188R71H102KA01D	1
DNP	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	C9	0603L	GRM1885C1H101JA01D	1
C0603C225K9PACTU	CAP, CERM, 2.2uF, 6.3V, +/-10%, X5R, 0603	C10, C11, C14, C19	0603	C0603C225K9PACTU	4
06033C104JAT2A	CAP, CERM, 0.1uF, 25V, +/-5%, X7R, 0603	C17	0603L	06033C104JAT2A	1
EMVY500GTR471MMH0S	CAP, AL, 470uF, 50V, +/-20%, 0.087 ohm, SMD	Cin1	CAPSMT_62_MH0	EMVY500GTR471MMH0S	1
GRM31CR61H225KA88L	CAP, CERM, 2.2uF, 50V, +/-10%, X5R, 1206	Cin2, Cin3, Cin4, Cin5	1206L	GRM31CR61H225KA88L	4
GRM32CR72A105KA35L	CAP, CERM, 1 µF, 100 V, +/- 10%, X7R, 1210	CO1, CO2, CO3, CO4, CO5	1210	GRM32CR72A105KA35L	5
5007	Test Point, Compact, White, TH	COMP, SS, SW1, SW2	Keystone5007	5007	4
EEV-FK2A221M	CAP, AL, 220uF, 100V, +/-20%, 0.153 ohm, SMD	Cout1, Cout2	SM_RADIAL_K16	EEV-FK2A221M	2
06031C152KAT2A	CAP, CERM, 1500 pF, 100 V, +/- 10%, X7R, 0603	Cx	0603	06031C152KAT2A	1
MBR1H100SFT3G	Diode, Schottky, 100V, 1A, SOD-123FL	D1, D2, D3	SOD-123FL	MBR1H100SFT3G	3
5006	Test Point, Compact, Black, TH	Gnd, Gnd1, ICGnd	Keystone5006	5006	3
VIN	Terminal 50A Lug	J1	CB35-36-CY	CB35-36-CY	1
GND	Terminal 50A Lug	J2, J4	CB35-36-CY	CB35-36-CY	2
VOUT	Terminal 50A Lug	J3	CB35-36-CY	CB35-36-CY	1
SER2817H-103KL	Inductor, Shielded Drum Core, Ferrite, 10uH, 28A, 0.00256 ohm, SMD	L1	IND_SER2817	SER2817H-103KL	1
MMBT3904T-7-F	Transistor, NPN, 20V, 0.2A, SOT-523	Q1, Q3, Q5, Q7	SOT-523	MMBT3904T-7-F, Diodes Inc.	4
DNP	TRANS PNP 40V 200MA SOT523	Q2, Q4, Q6, Q8	SOT-523	MMBT3906, Fairchild S	4
BSC123N08NS3 G	MOSFET, N-CH, 80V, 55A, PG-TDSON-8	Qh1, Qh2, Ql1, Ql2	PG-TDSON-8	BSC123N08NS3 G	4
CRCW0603100KFKEA	RES, 100k ohm, 1%, 0.1W, 0603	R1	0603L	CRCW0603100KFKEA	1
CRCW060351K1FKEA	RES, 51.1k ohm, 1%, 0.1W, 0603	R2	0603L	CRCW060351K1FKEA	1
CRCW06030000Z0EA	RES, 0 ohm, 5%, 0.1W, 0603	R3, R5, R7, R14, R15, R16, Rh2, Rl1	0603L	CRCW06030000Z0EA	8
CRCW06031K00JNEA	RES, 1.0k ohm, 5%, 0.1W, 0603	R4	0603	CRCW06031K00JNEA	1
CRCW0603240KJNEA	RES, 240k ohm, 5%, 0.1W, 0603	R6	0603L	CRCW0603240KJNEA	1
CRCW0603140KFKEA	RES, 140k ohm, 1%, 0.1W, 0603	R8	0603L	CRCW0603140KFKEA	1

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RC0603JR-0722KL	RES, 22 k, 5%, 0.1 W, 0603	R9	0603	RC0603JR-0722KL	1
CRCW0603330RJNEA	RES, 330 ohm, 5%, 0.1W, 0603	R10	0603	CRCW0603330RJNEA	1
CRCW060322K0JNEA	RES, 22k ohm, 5%, 0.1W, 0603	R11	0603	CRCW060322K0JNEA	1
CRCW06031K00FKEA	RES, 1.00k ohm, 1%, 0.1W, 0603	R12, R13	0603L	CRCW06031K00FKEA	2
CRCW0603100RFKEA	RES, 100, 1%, 0.1 W, 0603	R17	0603	CRCW0603100RFKEA	1
CRCW060310K0FKEA	RES, 10.0k ohm, 1%, 0.1W, 0603	R18	0603L	CRCW060310K0FKEA	1
CRCW06032R20JNEA	RES, 2.2 ohm, 5%, 0.1W, 0603	Rh1, Rl2	0603	CRCW06032R20JNEA	2
WSL2512R0150FEA	RES, 0.015 ohm, 1%, 1W, 2512	Rs1, Rs2, Rs3	2512M	WSL2512R0150FEA	3
WSL2512R0100FEA	RES, 0.01 ohm, 1%, 1W, 2512	Rs4	2512M	WSL2512R0100FEA	1
CRCW12061R78FKEA	RES, 1.78, 1%, 0.25 W, 1206	Rx, Rx1	1206	CRCW12061R78FKEA	2
LM5175	60V, Wide VIN, 4 switch Sync Buck-Boost Controller TSSOP28	U1	TPS43601	TPS43601	1
5005	Test Point, Compact, Red, TH	Vin, Vout	Keystone5005	5005	2

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